# **INTEGRATED CIRCUITS**

# DATA SHEET



MPEG) Multichannel

# SAA2505H DUET digital multichannel audio IC

Preliminary specification Supersedes data of 1998 Mar 10 File under Integrated Circuits, IC01 2001 Apr 05





# **SAA2505H**

#### **FEATURES**

#### Hardware features

- Two 40 MIPS 20-bit DSP cores
- · All input and output buffer RAM is on-chip
- · Program ROM on-chip for all decoding modes
- Two I<sup>2</sup>S-bus inputs with normal, double and quad speed mode (slave only)
- Second serial input usable for ADC (Karaoke input)
- Three normal and double speed I<sup>2</sup>S-bus outputs (slave and master from 256 and 384f<sub>s</sub>)
- One normal, double, quad speed I<sup>2</sup>S-bus output (slave and master from 256 and 384f<sub>s</sub>)
- Japanese EIAJ serial input and output formats
- Sony Philips Digital Interface (SPDIF) output
- I<sup>2</sup>C-bus control (up to 400 kHz)
- 3.3 V supply with 5 V TTL compatible inputs/outputs
- · Boundary scan for printed-circuit board testing.

#### Software features

- AC-3 up to 5.1 channels
- MPEG 2 L2 up to 7.1 channels
- MPEG 1 L2 (Video-CD) 2 channels at 44.1 kHz
- Dolby pro-logic decoding at 32, 44.1 and 48 kHz
- Output configuration for 7, 5, 4, 3, 2 and 1 channels with or without Low Frequency Enhancement (LFE)
- Bass redirection for small satellite loudspeakers plus subwoofer
- · Karaoke voice mix
- Dynamic range compression (AC-3 and MPEG)
- Adjustable delay up to 15 ms for surround channels (1.5 kbyte words)
- Adjustable delay up to 5 ms for centre channel (250 words)
- · Rounding to DAC word length
- Mute by pin and I<sup>2</sup>C-bus command
- AC-3 and MPEG bitstream information available via the l<sup>2</sup>C-bus
- · Concealment of CRC errors
- · SPDIF coded output
- Fully programmable SPDIF channel status information.



#### **APPLICATIONS**

The SAA2505H is intended for all markets where a multi-channel audio decoder for Dolby AC-3 and MPEG 2 is required.

Primary markets are for DVD video players, TV sets and audio/video amplifiers.

#### **GENERAL**

The SAA2505H decodes multi-channel audio up to MPEG 7.1, AC-3 5.1 and pro-logic on a dual DSP core.

The device contains all of the RAM and ROM necessary for operation. This minimises the need for external components and no microcode download is required.

The device is primarily intended for audio/video surround sound amplifiers where the amplifier is connected to the data source by means of SPDIF (IEC 60958). The input interface is, therefore, made for SPDIF (IEC 60958) and formatted for the I<sup>2</sup>S-bus.

The primary device output is PCM, sent via four I<sup>2</sup>S-bus ports. There is also a SPDIF (IEC 60958) formatted output.

User control is achieved via an I<sup>2</sup>C-bus. However, the SAA2505H is capable of stand-alone operation.



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# **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{DDD}$	digital supply voltage		3.0	3.3	3.6	V
I <sub>DDD</sub>	digital supply current		_	160	_	mA
$V_{DDA}$	analog supply voltage		3.0	3.3	3.6	V
I <sub>DDA</sub>	analog supply current		_	tbf	_	mA
f <sub>xtal</sub>	crystal frequency		_	35	_	MHz
T <sub>amb</sub>	operating ambient temperature		0	_	70	°C
V <sub>ESD</sub>	electrostatic discharge sensitivity	note 1	-2000	_	+2000	V
	for all pins	note 2	-300	_	+300	V

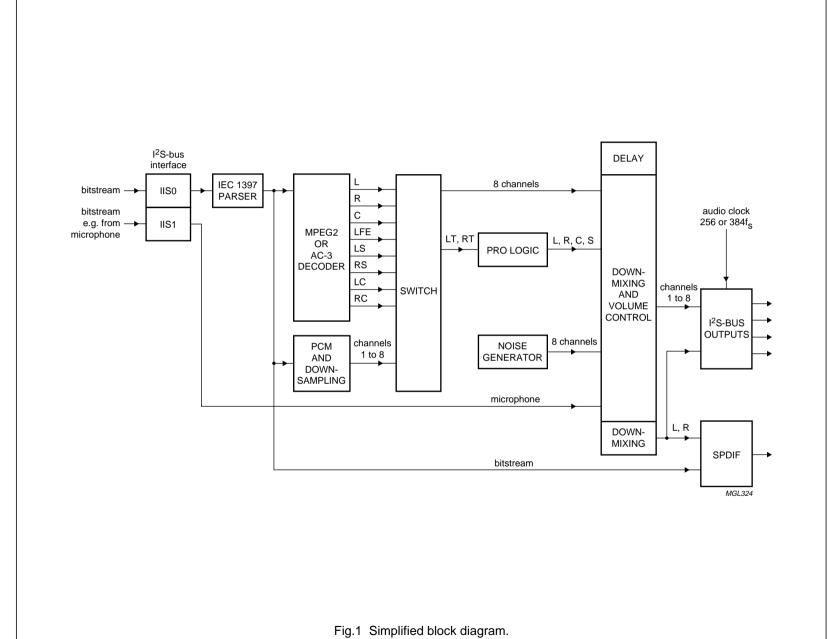
# **Notes**

- 1. Human body model: equivalent to discharging a 100 pF capacitor through a 1500  $\Omega$  resistor.
- 2. Machine model: equivalent to discharging a 200 pF capacitor through a 0  $\Omega$  resistor.

# **ORDERING INFORMATION**

TYPE		PACKAGE				
NUMBER	NAME	NAME DESCRIPTION VERSION				
SAA2505H	QFP64	plastic quad flat package; 64 leads (lead length 1.6 mm); body $14 \times 14 \times 2.7$ mm	SOT393-1			

**BLOCK DIAGRAM** 



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# **PINNING**

SYMBOL	PIN	DRIVE/ LOAD(1)	TYPE	DESCRIPTION
STANDALONE	1	Α	I	select stand-alone mode input
EFO1	2	F	0	output flag FO1; from DSP2
EFO2	3	F	0	output flag FO2; from DSP2
EFO3	4	F	0	output flag FO3; from DSP2
EFO4	5	F	0	output flag FO4; from DSP1
EFO5	6	F	0	output flag FO5; from DSP1
EFO6	7	F	0	output flag FO6; from DSP1
V <sub>SSDI</sub>	8	_	S	digital ground for internal logic and memories; note 2
V <sub>DDDI</sub>	9	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
EFI1	10	Α	I	input flag FI1; to DSP2
EFI2	11	Α	I	input flag FI2; to DSP1
EFI3	12	Α	I	input flag FI3; to DSP1
V <sub>DDDE</sub>	13	_	S	digital supply voltage for I/O cells (+3.3 V); note 4
WSO	14	G	I/O	word select input/output for ports 0 to 2; also used for output port 3 when not in quad mode (I <sup>2</sup> S-bus)
SCK	15	G	I/O	serial clock input/output for ports 0 to 2; also used for output port 3 when not in quad mode (I <sup>2</sup> S-bus)
V <sub>SSDE</sub>	16	_	S	digital ground for I/O cells; note 5
SDO0	17	F	0	serial data output for port 0 (I <sup>2</sup> S-bus)
SDO1	18	F	0	serial data output for port 1 (I <sup>2</sup> S-bus)
$V_{DDDE}$	19	_	S	digital supply voltage for I/O cells (+3.3 V); note 4
V <sub>SSDI</sub>	20	_	S	digital ground for internal logic and memories; note 2
$V_{DDDI}$	21	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V <sub>SSDI</sub>	22	_	S	digital ground for internal logic and memories; note 2
$V_{DDDI}$	23	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
$V_{DDDI}$	24	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V <sub>SSDI</sub>	25	_	S	digital ground for internal logic and memories; note 2
$V_{DDDE}$	26	_	S	digital supply voltage for I/O cells (+3.3 V); note 4
SDO2	27	F	0	serial data output for port 2 (I <sup>2</sup> S-bus)
SDO3	28	F	0	serial data output for port 3 (I <sup>2</sup> S-bus)
V <sub>SSDE</sub>	29	_	S	digital ground for I/O cells; note 5
WSO3	30	F	0	word select output for port 3; used in quad mode (I <sup>2</sup> S-bus)
SCKO3	31	F	0	serial clock output for port 3; used in quad mode (I <sup>2</sup> S-bus)
V <sub>DDDE</sub>	32	_	S	digital supply voltage for I/O cells (+3.3 V); note 4
SDB	33	F	0	serial data begin output for port 3; used in quad mode (I <sup>2</sup> S-bus)
SPDIF	34	F	0	SPDIF output
V <sub>SSDE</sub>	35	_	S	digital ground for I/O cells; note 5
V <sub>SSDI</sub>	36	_	S	digital ground for internal logic and memories; note 2
V <sub>DDDI</sub>	37	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3

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SYMBOL	PIN	DRIVE/ LOAD <sup>(1)</sup>	TYPE	DESCRIPTION
V <sub>SSDE</sub>	38	_	S	digital ground for I/O cells; note 5
SYSCLK	39	Е	0	programmable system clock output
V <sub>DDDE</sub>	40	_	S	digital supply voltage for I/O cells (+3.3 V); note 4
$V_{DDA}$	41	_	S	analog supply voltage for crystal oscillator (+3.3 V)
CLKI	42	Н	I	oscillator input
CLKO	43	Н	0	oscillator output
V <sub>SSDA</sub>	44	_	S	digital ground for crystal oscillator
ACLK	45	Α	I	audio clock input for master mode
V <sub>SSDE</sub>	46	_	S	digital ground for I/O cells; note 5
TDI	47	В	I	boundary scan test data input (this pin should be pulled HIGH for normal operation)
TMS	48	В	I	boundary scan test mode select input (this pin should be pulled HIGH for normal operation)
TCK	49	В	I	boundary scan test clock input
TRST	50	В	I	boundary scan test reset input (this pin should be pulled LOW for normal operation)
TDO	51	В	0	boundary scan test data output
$V_{DDDI}$	52	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
V <sub>SSDI</sub>	53	_	S	digital ground for internal logic and memories; note 2
WSI	54	Α	I	word select input for ports 0 and 1 (I <sup>2</sup> S-bus)
SDBI	55	Α	I	serial data begin input for port 0 (I <sup>2</sup> S-bus)
SDI0	56	Α	I	serial data input for port 0 (I <sup>2</sup> S-bus)
SDI1	57	Α	I	serial data input for port 1 (I <sup>2</sup> S-bus)
SCKI	58	Α	I	serial clock input for ports 0 and 1 (I <sup>2</sup> S-bus)
V <sub>SSDI</sub>	59	_	S	digital ground for internal logic and memories; note 2
$V_{DDDI}$	60	_	S	digital supply voltage for internal logic and memories (+3.3 V); note 3
RESET	61	С	I	hardware reset
ADDR	62	А	I	select address input (I <sup>2</sup> C-bus)
SCL	63	С	I	serial clock input; external pull-up to +5 V (I <sup>2</sup> C-bus)
SDA	64	D	I/O	serial data input/output; external pull-up to +5 V (I <sup>2</sup> C-bus)

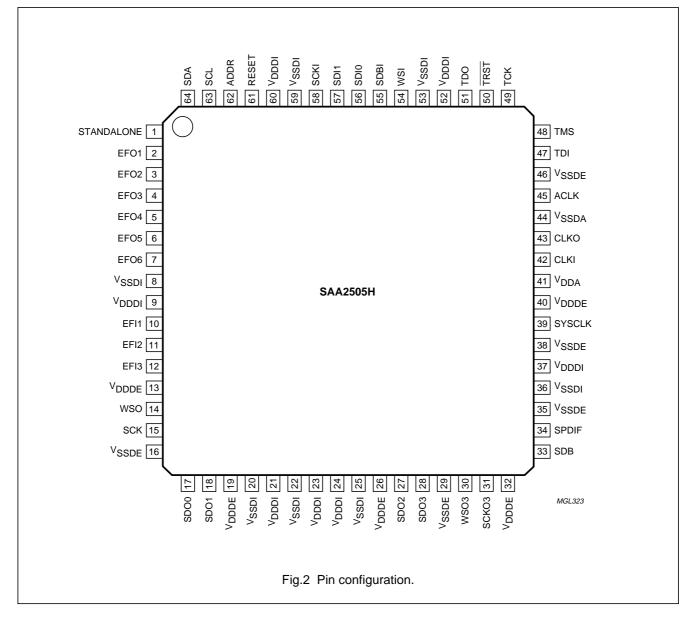
# **Notes**

- 1. See Table 1.
- 2. All  $V_{\text{SSDI}}$  pins are internally connected.
- 3. All  $V_{\text{DDDI}}$  pins are internally connected.
- 4. All  $V_{\text{DDDE}}$  pins are internally connected.
- 5. All  $V_{\mbox{\scriptsize SSDE}}$  pins are internally connected.

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Table 1 Pin drive and load descriptions

DRIVE/LOAD	DESCRIPTION
А	+5 V tolerant input; TTL characterized with internal pull-down resistor
В	+5 V tolerant input; TTL characterized with internal pull-up resistor
С	+5 V tolerant input; TTL Schmitt-trigger characterized
D	+5 V tolerant 400 kHz (I <sup>2</sup> C-bus)
Е	TTL characterised +5 V tolerant 3-state output with 3 mA drive capability
F	TTL characterised +5 V tolerant 3-state slew rate limited output with 3 mA drive capability
G	+5 V tolerant bidirectional 3-state pin; with 3 mA output drive and slew rate limiting; TTL level input; without pull-up or pull-down resistor
Н	crystal pins



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#### **CLOCK BUILD-UP**

Up to four clocks provide the timing information for the SAA2505H. These are as follows:

- 1. Data source clock
- 2. Data processing clock
- 3. I<sup>2</sup>C-bus data/control clock
- 4. Data sink clock.

#### Data source clock

Clocking of the input data is derived from the serial clock input at pin 58 and is compliant with the I<sup>2</sup>S-bus and EIAJ transfer formats. The ports are capable of operating at normal, double and quad speed.

#### Data processing clock

This clock is used for data processing and internal data transfer. The clock can either be provided by an external clock generator having a duty cycle between 40 and 60% or by using the internal crystal clock generator and an external crystal. The external clock should be connected between pins 42 (CLKI) and 43 (CLKO) (see Fig.11).

To use the internal clock a 35 MHz crystal operating on the 3rd harmonic must be connected between pins 42 and 43 (CLKI and CLKO).

A buffered version of this clock is available at pin 39 (SYSCLK). This can be optionally disabled or, a divided version (4, 2 and 1) of the clock input at pin 42 (CLKI) can be made available.

# I<sup>2</sup>C-bus data/control clock

The I<sup>2</sup>C-bus control logic supports I<sup>2</sup>C-bus clock speeds up to 400 kHz. This is supplied to pin 63 (SCL). If the SAA2505H is in the stand-alone mode (pin 1 HIGH) no I<sup>2</sup>C-bus clock needs to be supplied.

### Data sink clock

The data sink clock source is dependant on the mode of operation of the I<sup>2</sup>S-bus output ports.

In the master mode the  $I^2S$ -bus clock is derived form an external 256 or  $384f_s$  source connected to pin 45 (ACLK). This is internally divided and used to drive the serial clock at pins 15 and 31 (SCK and SCKO3). To ensure that the digital outputs poses good timing qualities (jitter and wander) pin 45 should be a connected to a high quality timing source.

In the I<sup>2</sup>S-bus slave mode the output data is clocked to pin 15. This can either be the serial clock input at pin 58 (SCKI) or a suitable external clock. When in slave mode the signal at pin 15 is replicated at pin 31.

#### **FUNCTIONAL DESCRIPTION**

#### Data sinks

Coded audio data or PCM audio data can be input to both DSPs from two slave-only serial interfaces capable of receiving data in either I<sup>2</sup>S-bus or EIAJ formats. Both serial interfaces use the same serial clock (pin 58) and word select input (pin 54). The serial clock must be at least 32f<sub>s</sub>.

Serial data is applied to pins 56 and 57 (SDI0 and SDI1). These pins are mode shared between the I<sup>2</sup>S-bus and EIAJ formatted serial data. Port mode selection is achieved via the I<sup>2</sup>C-bus interface, see Table 3.

# I<sup>2</sup>S-BUS FORMATTED SPDIF INFORMATION

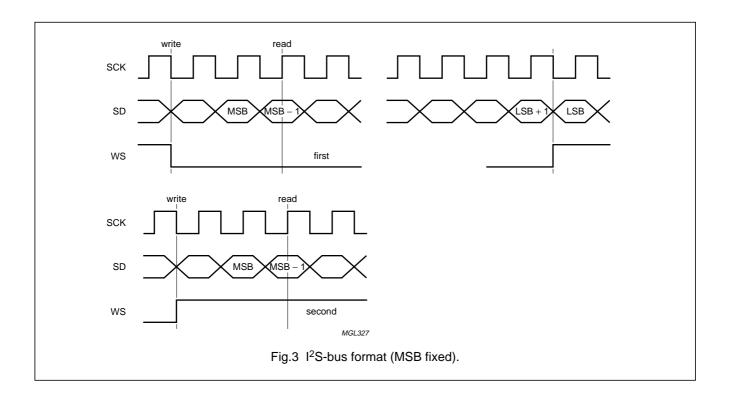
In the I<sup>2</sup>S-bus mode 'big-endian' data is received, MSB justified to 1 clock period after a falling edge of the word select output. The data stream should be formatted according to "IEC 60958 - SPDIF" including the extensions for non-PCM encoded audio data ("IEC 61937").

AC-3 and MPEG coded data is formatted in 16-bit words. These words are expected at a sample rate ( $f_s$ ) of 48 kHz and thus a minimum serial clock of 1.536 MHz; two 16-bit words per word select period. If the transmission word length is in excess of 16 bits all additional bits are discarded

PCM sample lengths of up to 20-bit words are supported with sample rates of 44.1 and 48 kHz. This mode is used to transfer PCM and PCM with Dolby pro-logic encoded data. Word select LOW corresponds to transmission of data for the left channel, word select HIGH corresponds to transmission of data for the right channel.

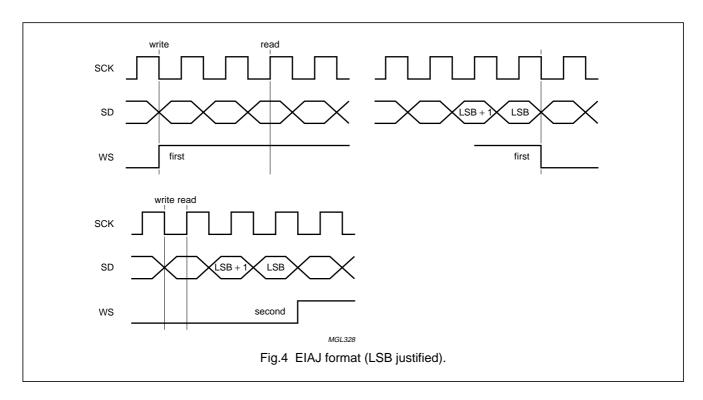
Pin 55 (SDBI) is reserved for a multi-channel extension to the I<sup>2</sup>S-bus and is currently not supported.

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# **EIAJ** FORMATTED INPUTS

In EIAJ mode 'big-endian' data is received LSB justified to the rising edge of word select output. Formatting of the data is identical to that used in the  $I^2S$ -bus mode.



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#### **Data sources**

I2S-BUS AND EIAJ FORMATTED OUTPUTS

The device has four I<sup>2</sup>S-bus/EIAJ mode select outputs. These outputs are capable of outputting data in EIAJ 20, 18 or 16-bit and I<sup>2</sup>S-bus modes. The EIAJ outputs are capable of operating in single or double speed, the I<sup>2</sup>S-bus output is capable of operating in single, double and quad speed.

The output ports can either be in the slave or master mode. In the slave mode they can either be slaved to the  $\rm I^2S$ -bus serial clock input (pin 15) or to an external clock. In the master mode an audio clock is applied to pin 45 that is 256 or  $384f_s$ . The master clocking scheme allows the support of a 96 kHz sample rate DAC by use of the double speed output option. The quad speed output option is intended to allow multiple SAA2505H devices to be connected together.

In order to obtain a high quality digital output in the master mode the audio clock should be of high quality, having low iitter and an even mark space ration.

#### SPDIF FORMATTED OUTPUT

The SPDIF output can transmit either coded data, as received from the serial data input at pin 56 (SDI0), or down-mixed 20-bit PCM stereo. The down-mixed stereo may be Pro-logic encoded.

Together with the PCM samples additional control bits are transmitted. These are the channel status, user data and validity bits.

The first five bytes of the channel status bits are user programmable, all following bytes are zeroed automatically. Transmission is LSB first.

The user data can carry message lengths of 129 bytes. These are transmitted over the SPDIF port at a rate of 2 bits per stereo sample. The message buffer of 129 bytes is loaded via the I<sup>2</sup>C-bus, if no message is written the SAA2505H outputs all zeros for the user data.

Table 2 Output port timing information

MODE	AUDIO CLOCK SAMPLING FREQUENCY	WORD SELECT SAMPLING FREQUENCY	SERIAL CLOCK SAMPLING FREQUENCY	SERIAL DATA BEGIN SAMPLING FREQUENCY
Single	256 or 384f <sub>s</sub>	1f <sub>s</sub>	64f <sub>s</sub>	-
Double	256 or 384f <sub>s</sub>	2f <sub>s</sub>	128f <sub>s</sub>	_
Quad	256f <sub>s</sub>	4f <sub>s</sub>	256f <sub>s</sub>	1f <sub>s</sub>
Quad	384f <sub>s</sub>	4f <sub>s</sub>	192f <sub>s</sub>	1f <sub>s</sub>

# **Control Inputs**

The SAA2505H can be operated in two stand-alone modes or can be managed by the I<sup>2</sup>C-bus.

STAND-ALONE MODES

Two stand-alone modes exist to allow the device to be used in systems without a microcontroller. These two modes are STANDALONE (pin 1) held HIGH and STANDALONE connected to RESET (pin 61).

When pin 1 is LOW a reset defaults the outputs to quiet, however when pin 1 is HIGH a reset defaults the I<sup>2</sup>S-bus output to active and the SPDIF output to mute. When pin 1 is HIGH some of the I<sup>2</sup>C-bus registers cannot be accessed see Table 3.

I<sup>2</sup>C-BUS REGISTER CONTROL

The  $I^2C$ -bus port supports 5 V, 400 kHz operation. The details of the registers are given in Table 3.

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OFOTION	DECICTED NAME	MEMORY	DEI	FAULT VA	LUE	DESCRIPTION
SECTION	REGISTER NAME	ADDRESS	<b>1</b> (1)	<b>2</b> <sup>(2)</sup>	<b>3</b> (3)	DESCRIPTION
General	SOFT_RESET	\$8 000-b0	0	0	0	0: operation
						1: reset
General	SYSCLCKEN	\$8 000-b1	0	note 4	1	0: enable SYSCLK output
						1: disable SYSCLK output
General	SYSCLKDIV	\$8 000-b3 and b2	00	note 4	10	00: SYSCLK = 1/4CLK
						01: SYSCLK = $\frac{1}{2}$ CLK
						10: SYSCLK = CLK
						11: reserved
General	EN_INP_INT_DSP1	\$8 000-b4	0	note 4	1	0: disable input interrupts on DSP1
						1: enable input interrupts on DSP1
General	EN_OUTP_INT_DSP1	\$8 000-b5	0	note 4	0	0: disable output interrupts on DSP1
						1: enable output interrupts on DSP1
General	EN_INP_INT_DSP1	\$8 000-b6	0	note 4	1	0: disable input interrupts on DSP2
						1: enable input interrupts on DSP2
General	EN_OUTP_INT_DSP1	\$8 000-b7	0	note 4	0	0: disable output interrupts on DSP2
						1: enable output interrupts on DSP2
General	ACLKSEL	\$8 000-b8	0	note 4	0	0: ACLK = 256f <sub>s</sub>
						1: ACLK = 384f <sub>s</sub>
General	MEMCONFIG	\$8 000-b9	0	note 4	0	0: program memory on DSP1 = 12 kbytes
						0: program memory on DSP2 = 8 kbytes
						1: program memory on DSP1 = 8 kbytes
						1: program memory on DSP2 = 12 kbytes
I <sup>2</sup> SCONTROL	IISMODE	\$8 001-b1 and b0	00	note 4	00	00: I <sup>2</sup> S-bus/EIAJ input format
						01: reserved
						10: reserved
						11: reserved
I <sup>2</sup> SCONTROL	IISINP	\$8 001-b2	0	note 4	0	0: I <sup>2</sup> S-bus input format
						1: EIAJ 16-bit input format
I <sup>2</sup> SCONTROL	IISI_SDB_EN	\$8 001-b3	0	note 4	0	0: SDBI is DSP1 Input flag
						1: SDBI is aligned to WS to allow multi-channel I <sup>2</sup> S-bus input

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2=2=1211		MEMORY	DEI	AULT VA	LUE	
SECTION	REGISTER NAME	ADDRESS	<b>1</b> (1)	<b>2</b> (2)	<b>3</b> (3)	DESCRIPTION
I <sup>2</sup> SCONTROL	reserved	\$8 001-b4	0	note 4	0	reserved
I <sup>2</sup> SCONTROL	IISOUTMOD	\$8 001-b6 and b5	00	note 4	00	00: I <sup>2</sup> S-bus format data output
						01: EIAJ 16-bit format data output
						10: EIAJ 18-bit format data output
						11: EIAJ 20-bit format data output
I <sup>2</sup> SCONTROL	IISOUTMST	\$8 001-b7	0	note 4	0	0: I <sup>2</sup> S-bus outputs are slaves
						1: I <sup>2</sup> S-bus outputs are masters
I <sup>2</sup> SCONTROL	IISOUTSPD	\$8 001-b8	0	note 4	0	0: I <sup>2</sup> S-bus outputs 0 to 2 operate at normal speed
						1: I <sup>2</sup> S-bus outputs 0 to 2 operate at double speed
I <sup>2</sup> SCONTROL	IIS3OUTSPD	\$8 001-b10 and b9	00	note 4	00	00: I <sup>2</sup> S-bus output 3 operates at normal speed
						01: I <sup>2</sup> S-bus output 3 operates at double speed
						10: I <sup>2</sup> S-bus output 3 operates at quad speed
						11: I <sup>2</sup> S-bus output 3 operates at normal speed
I <sup>2</sup> SCONTROL	IISO0EN	\$8 001-b11	0	note 4	1	0: SDO0 output 3-stated
						1: SDO0 output enabled
I <sup>2</sup> SCONTROL	IISO1EN	\$8 001-b12	0	note 4	1	0: SDO1 output 3-stated
						1: SDO1 output enabled
I <sup>2</sup> SCONTROL	IISO2EN	\$8 001-b13	0	note 4	1	0: SDO2 output 3-stated
						1: SDO2 output enabled
I <sup>2</sup> SCONTROL	IISO3EN	\$8 001-b14	0	note 4	1	0: SDO3 output 3-stated
						1: SDO3 output enabled
I <sup>2</sup> SCONTROL	IIS3CLKEN	\$8 001-b15	0	note 4	0	0: SCKO3, WSO3 and SDB outputs 3-stated
						1: SCKO3, WSO3 and SDB outputs enabled
SPDIF1	SPDIFVAL	\$8 002-b0	0	0	0	0: SPDIF validity bit = 0
						1: SPDIF transmitting valid PCM
SPDIF1	SPDIFBYP	\$8 002-b1	0	0	0	0: output PCM data from DSP1
						1: output I <sup>2</sup> S-bus data from I <sup>2</sup> S-bus input
SPDIF1	IISUBIT	\$8 002-b2	0	0	0	reserved
SPDIF1	SPDIFEN	\$8 002-b3	0	0	0	0: 3-state SPDIF output and reset SPDIF block
						1: enable SPDIF output

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Preliminary specification

CECTION	ECTION DECISTED NAME	MEMORY	DEF	AULT VA	LUE	DECORIDEION
SECTION REGISTER NAME	ADDRESS	<b>1</b> <sup>(1)</sup>	<b>2</b> <sup>(2)</sup>	<b>3</b> (3)	DESCRIPTION	
Normal usage	•	•			•	
SPDIF1	CSBYTE0	\$8 002-b15 to b8	0000	0000		b8: consumer mode
						b9: LPCM
				<u> </u>		b10: copy protection
						b11 to b13: pre-emphasis
						b14 to b15: mode
SPDIF2	CSBYTE1	\$8 003-b7 to b0	0000	0000		b0 to b7: category code
SPDIF2	CSBYTE2	\$8 003-b15 to b8	0000	0000		b8 to b11: source
						b12 to b15: channel number
SPDIF3	CSBYTE3	\$8 003-b7 to b0	0000	0000 0000		b0 to b3: source
						b4 to b6: clock accuracy
SPDIF3	CSBYTE4	\$8 003-b15 to b8	0000	0000		b0 to b3: word length

# Notes

- 1. STANDALONE held LOW.
- 2. STANDALONE held HIGH.
- 3. STANDALONE connected to RESET.
- 4. Controlled by DSP; no I<sup>2</sup>C-bus access.

All unused bits return a value of 0.

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## I<sup>2</sup>C-bus control and commands (pins 63 and 64)

#### INTRODUCTION

A general description of "The I<sup>2</sup>C-bus and how to use it" can be obtained from Philips sales offices using ordering number 9398 393 40011.

For the external control of the SAA2505H a fast I<sup>2</sup>C-bus is implemented. This is a 400 kHz bus which is downward compatible with the standard 100 kHz bus. There are two different types of control instructions:

- Instructions to control the DSP program; programming the coefficient RAM and reading the values of parameters
- Instructions controlling source selection and programmable parts; through the control registers as detailed in Table 3.

The detailed description of the I<sup>2</sup>C-bus and commands is given in the following sections.

### CHARACTERISTICS OF THE I<sup>2</sup>C-BUS

The I<sup>2</sup>C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are the serial data line (SDA) and the serial clock line (SCL). Both lines must be connected to the supply rail via a pull-up resistor when connected to the output stages of a microcontroller. For a 400 kHz I<sup>2</sup>C-bus, the recommendation from Philips Semiconductors must be followed (e.g. up to loads of 200 pF on the bus a pull-up resistor can be used, between 200 and 400 pF a current source or switched resistor must be used). Data transfer can only be initiated when the bus is not busy.

#### **BIT TRANSFER**

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals. The maximum clock frequency is 400 kHz. To be able to run at this high frequency all of the Inputs and outputs connected to the bus must be designed for this high speed I<sup>2</sup>C-bus according the Philips specification (see Fig.5).

#### START AND STOP CONDITIONS

Both data and clock line will remain HIGH when the bus in not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as a STOP condition (P) (see Fig.6).

A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as a START condition (S) (see Fig.6).

#### **DATA TRANSFER**

A device generating a message is a 'transmitter', a device receiving a message is the 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves' (see Fig.7).

#### **ACKNOWLEDGE**

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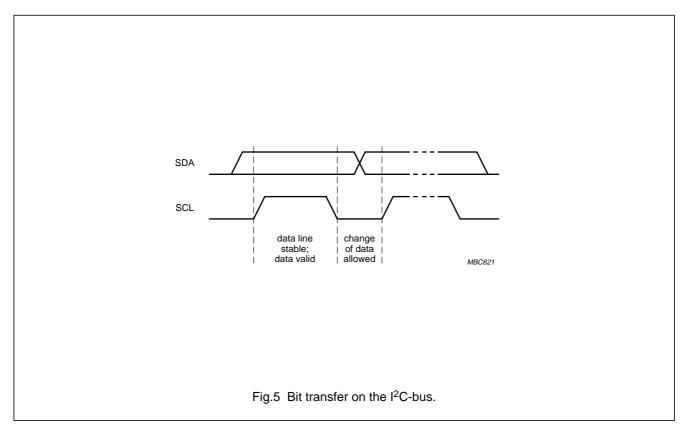
The number of data bits transferred between the START and STOP conditions from the transmitter to the receiver is not limited. Each byte of 8 bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level left on the bus by the transmitter whereas the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull-down the SDA line, left HIGH by the transmitter, during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Set-up and hold times must be taken into account. A master receiver must signal an end-of-data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition (see Fig.8).

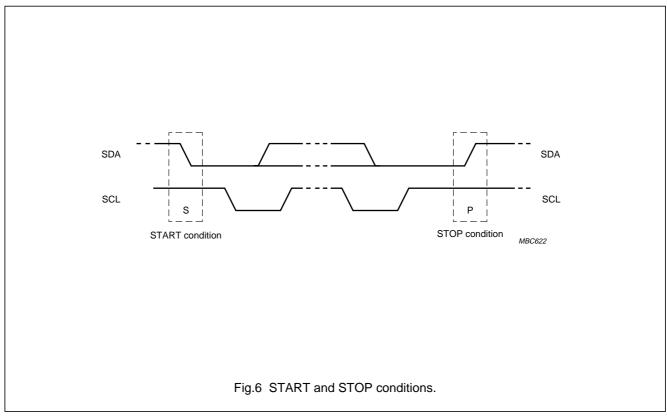
State of the  $I^2C$ -bus interface during and after power-on reset

During power-on reset the internal SDA line is kept HIGH and the SDA pin is therefore high impedance. The SDA line remains HIGH until a master pulls it down to initiate communication.

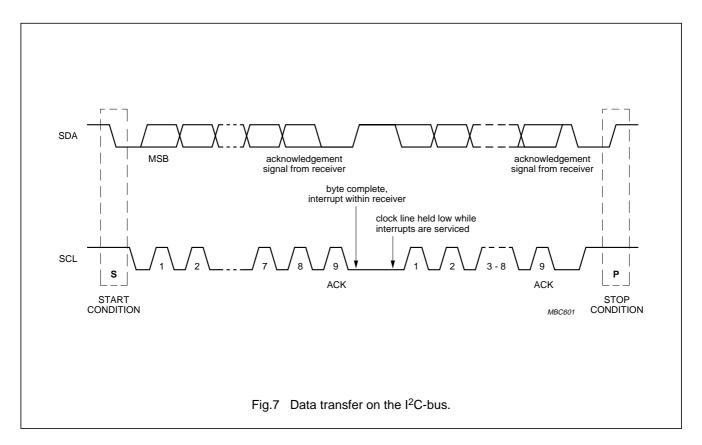
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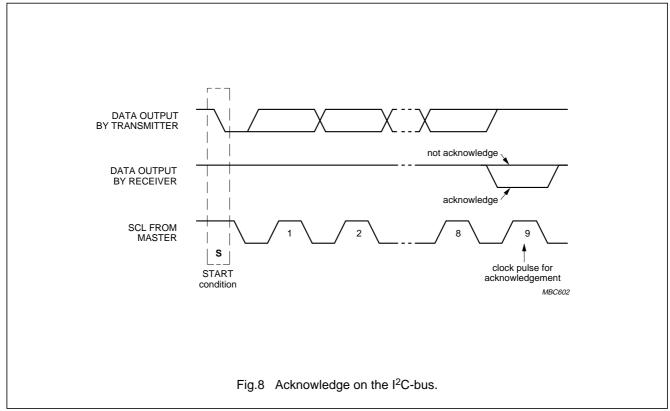
**SAA2505H** 





# **SAA2505H**





# DUET digital multichannel audio IC

**SAA2505H** 

#### I2C-bus format

#### **ADDRESSING**

Before any data is transmitted on the  $I^2C$ -bus, the device which should respond is addressed first. The addressing is always done with the first byte transmitted after the start procedure.

SLAVE ADDRESS SELECTION (PIN 62)

The SAA2505H acts as slave receiver or a slave transmitter. Therefore the clock signal (SCL) is only an input signal. The data signal (SDA) is a bidirectional line. The SAA2505H slave addresses are shown in Table 4.

Table 4 I<sup>2</sup>C-bus address

I <sup>2</sup> C-BUS LEVEL	I <sup>2</sup> C-BUS ADDRESS
1	59H
0	58H

The subaddress bit A0 corresponds to the hardware address at pin 52 which allows the device to have 2 different addresses. This allows control of two DUET ICs via the same I<sup>2</sup>C-bus.

WRITE AND READ CYCLES

The I<sup>2</sup>C-bus configuration for a write cycle is shown in Table 5. The write cycle is used to write the bytes to memory and control registers.

The I<sup>2</sup>C-bus configuration for a read cycle is shown in Table 6. The read cycle is used to read bytes from memory and control registers.

**Table 5** I<sup>2</sup>C-bus write sequence

I <sup>2</sup> C-BUS MASTER	SAA2505H
START	_
I <sup>2</sup> C-bus address of SAA2505H	_
Write	_
_	acknowledge
Address high part	_
_	acknowledge
Address low part	_
_	acknowledge
Data high part	_
_	acknowledge
Data medium part	_
_	acknowledge
Data low part	_
_	acknowledge
Data high part	_
_	acknowledge
Data medium part	_
_	acknowledge
Data low part	_
_	acknowledge
Continued exchange	es
STOP Condition	_

# DUET digital multichannel audio IC

**SAA2505H** 

**Table 6** I<sup>2</sup>C-bus read sequence

I <sup>2</sup> C-BUS MASTER	SAA2505H
START	-
I <sup>2</sup> C-bus address of SAA2505H	_
Write	_
_	acknowledge
Address high part	_
-	acknowledge
Address low part	_
_	acknowledge
START	_
I <sup>2</sup> C-bus address of SAA2505H	_
Read	-
_	acknowledge
_	data high part
_	acknowledge
_	data medium part
_	acknowledge
_	data low part
_	acknowledge
-	data high part
-	acknowledge
_	data medium part
_	acknowledge
-	data low part
_	acknowledge
Continued Exchang	es
STOP Condition	_

All RAM and peripheral registers are mapped into a common 16-bit address range. The data words are all MSB padded to 24-bit, however, the on-chip RAM is 20-bit and therefore the 4 MSBs are padded with zeros.

**Table 7** SAA2505H I<sup>2</sup>C-bus address ranges

START	STOP	MEMORY BLOCK
\$0	\$1FFF	DSP1 X memory
\$2000	\$3FFF	DSP1 Y memory
\$4000	\$5FFF	DSP2 X memory
\$6000	\$7FFF	DSP2 Y memory
\$8000	\$9FFF	control registers

# Power supply connections and EMC

The digital part of the chip has in total 13 positive supply line connections and 13 ground connections. To minimise radiation the device should be put on a double layer PCB with, on one side, a large ground plane. The ground supply lines should have a short connection to this ground plane. The supply line connections should have minimum inter-pin PCB track impedances. A low reactance (Q) ferrite bead/capacitor network in the positive supply line can be used as a high frequency filter. Special attention should be paid to the analog supply lines (VDDA and VSSA).

#### **Boundary scan test interface**

The SAA2505H has a 5 pin boundary scan test interface which implements the three required commands of the IEEE1149; BYPASS, SAMPLE and EXTEST.

The boundary scan test interface uses the following pins TDI (pin 47), TMS (pin 48), TCK (pin 49), TRST (pin 50) and TDO (pin 51). Naming and use of the pins is as per IEEE recommendations.

Though TRST, TMS and TDI have internal pull-up resistors there should also be system level pull-up resistors.

# DUET digital multichannel audio IC

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#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>DDD</sub>	digital supply voltage		-0.3	+3.3	V
$\Delta V_{DDD}$	voltage difference between two supply voltage pins		_	330	mV
I <sub>IK</sub>	DC input clamp diode current	$V_{I} < -0.3 \text{ V or } V_{I} > V_{DDD} + 0.3 \text{ V}$	_	±10	mA
I <sub>OK</sub>	DC output clamp diode current	output type 4 mA; $V_O < -0.3 \text{ V}$ or $V_O > V_{DDD} + 0.3 \text{ V}$	_	±10	mA
I <sub>O</sub>	DC output source or sink current	output type 4 mA; -0.3 V < V <sub>O</sub> < V <sub>DDD</sub> + 0.3 V	_	±10	mA
I <sub>DDD</sub> I <sub>SSD</sub>	DC current per supply pin (V <sub>DDD</sub> or V <sub>SSD</sub> )		_	±500	mA
T <sub>amb</sub>	operating ambient temperature		0	70	°C
T <sub>stg</sub>	storage temperature range		-55	+125	°C
LTCH	latch-up protection	CIC specification/test method	100	_	mA
V <sub>ESD</sub>	electrostatic discharge sensitivity	note 1	-2000	+2000	V
	for all pins	note 2	-300	+300	V

## **Notes**

- 1. Human body model: equivalent to discharging a 100 pF capacitor through a 1500  $\Omega$  resistor.
- 2. Machine model: equivalent to discharging a 200 pF capacitor through a 0  $\Omega$  resistor.

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient in free air	45	K/W

# **CHARACTERISTICS**

Digital I/O at  $T_{amb}$  = 0 to 70 °C;  $V_{DDD}$  = 3.0 to 3.6 V; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{DDD}$	digital supply voltage		3	3.3	3.6	V
$V_{DDA}$	analog supply voltage for the crystal oscillator		3	3.3	3.6	V
I <sub>DDD</sub>	digital supply current	f <sub>xtal</sub> = 41 MHz; maximum activity of the DSP	_	tbf	tbf	mA
I <sub>DD(xtal)</sub>	supply current for the crystal oscillator	f <sub>xtal</sub> = 41 MHz; functional mode	_	tbf	tbf	mA
P <sub>tot</sub>	total power dissipation	f <sub>xtal</sub> = 41 MHz; maximum activity of the DSP	_	tbf	tbf	W
V <sub>hys</sub>	schmitt trigger hysteresis	pin type SCHMITCD	0.4	_	0.7	V
V <sub>IH</sub>	HIGH-level input voltage	$I_o = -3$ mA; pin types A, B and C	2.0	_	_	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>DDD</sub> = 3.0 V; I <sub>o</sub> = 3 mA; pin types A, B and C	_	_	0.8	V

# DUET digital multichannel audio IC

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>OH</sub>	HIGH-level digital output voltage	$I_0 = -3$ mA; pin types A, B and C	2.4	_	-	V
V <sub>OL</sub>	LOW-level digital output voltage	$V_{DDD} = 3.0 \text{ V; } I_0 = 3 \text{ mA;}$ pin types A, B and C	_	_	0.4	V
V <sub>OL(I2C)</sub>	LOW-level digital output voltage and I <sup>2</sup> C-bus data output	I <sub>o</sub> = 8 mA; pin type D	_	_	0.4	V
I <sub>LO(Z)</sub>	output leakage current, 3-state outputs	$V_o = 0$ or $V_{DDD}$ ; pin types A, B and C	_	_	±5	μА
R <sub>pu(int)</sub>	internal pull-up resistor to V <sub>DDDX</sub>	pin type B	_	76	_	kΩ
R <sub>pd(int)</sub>	internal pull-down resistor to V <sub>SSDX</sub>	pin type A	_	76	_	kΩ
t <sub>i(r)</sub>	input rise time	V <sub>DDD</sub> = 3.6 V	_	tbf	3.6	ns
t <sub>i(f)</sub>	input fall time	V <sub>DDD</sub> = 3.6 V	_	tbf	3.6	ns
t <sub>o(r)</sub>	output rise time	pin types E, F and G; $V_{DDD} = 3.3 \text{ V}; T_{amb} = 25 ^{\circ}\text{C};$ process = 0 $\sigma$ ; $C_L = 20 \text{ pF}$	_	_	3.0	ns
t <sub>o(f)</sub>	output fall time	pin types E, F and G; $V_{DDD} = 3.3 \text{ V}; T_{amb} = 25 ^{\circ}\text{C};$ process = 0 $\sigma$ ; $C_L = 20 \text{ pF}$	-	_	3.5	ns
Oscillator	input/output					
f <sub>xtal</sub>	crystal frequency		40	40.5	_	MHz
V <sub>xtal</sub>	voltage across the crystal		3.0	3.3	3.6	V
g <sub>m</sub>	transconductance	at start-up	10.5	19	32	mS
		in operating range	3.6	_	38	mS
C <sub>L(CLK)</sub>	capacitive load of clock output		_	500	1000	fF
T <sub>cy(STRTU)</sub>	number of cycles in start-up time	depends on quality of the external crystal	_	1000	_	cycles

# DUET digital multichannel audio IC

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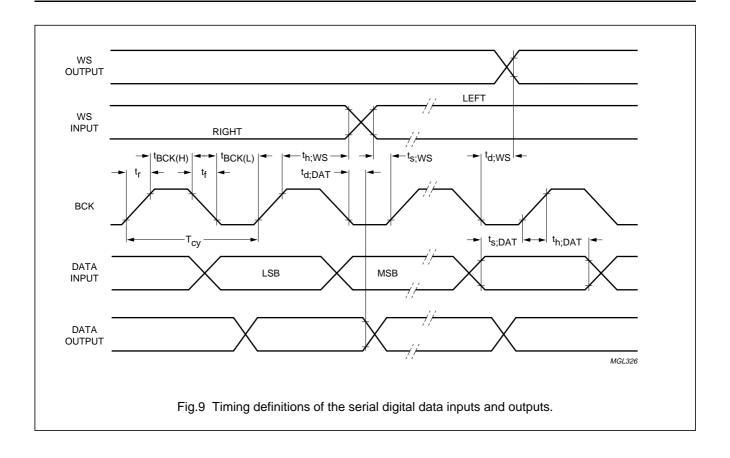
# **TIMING CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Serial digi	tal inputs and outputs; (see Fig.9)		•	!	•
t <sub>r</sub>	rise time	_	7.5	ns	
t <sub>f</sub>	fall time	T <sub>cy</sub> = 50 ns	_	7.5	ns
T <sub>cy</sub>	bit clock cycle time	,	70	_	ns
t <sub>BCK(H)</sub>	bit clock time HIGH	T <sub>cy</sub> = 50 ns	17.5	_	ns
t <sub>BCK(L)</sub>	bit clock time LOW	T <sub>cy</sub> = 50 ns	17.5	_	ns
t <sub>s;DAT</sub>	data set-up time host	T <sub>cy</sub> = 50 ns	320	_	ns
t <sub>s;DAT</sub>	data set-up time I <sup>2</sup> S-bus input		10	_	ns
t <sub>h;DAT</sub>	data hold time host	T <sub>cy</sub> = 50 ns	50	_	ns
t <sub>h;DAT</sub>	data hold time I <sup>2</sup> S-bus input	,	10	_	ns
t <sub>s;WS</sub>	word select set-up time I <sup>2</sup> S-bus input	T <sub>cy</sub> = 50 ns	100	_	ns
t <sub>h;WS</sub>	word select hold time I2S-bus input	T <sub>cy</sub> = 50 ns	100	_	ns
t <sub>d;DAT</sub>	data delay time host	,	_	20	ns
t <sub>d;WS</sub>	word select delay time host		_	15	ns
I <sup>2</sup> C-bus tir	ning; (see Fig.10)		•		
f <sub>SCL</sub>	SCL clock frequency		0	400	kHz
t <sub>BUF</sub>	bus free between a STOP and START condition		1.3	_	μs
t <sub>HD;STA</sub>	hold time (repeated) start condition; after this period the first clock pulse is generated		0.6	_	μs
$t_{LOW}$	LOW period of the SCL clock		1.3	_	μs
t <sub>HIGH</sub>	HIGH period of the SCL clock		0.6	_	μs
t <sub>SU;STA</sub>	set-up time for a repeated start condition		0.6	_	μs
t <sub>HD;DAT</sub>	data hold time		0	0.9	μs
t <sub>SU;DAT</sub>	data set-up time	for standard mode I <sup>2</sup> C-bus system t <sub>SU;DAT</sub> > 250 ns	100	_	ns
t <sub>r</sub>	rise time of both SDA and SCL	f <sub>SCL</sub> = 400 kHz	20 + 0.1C <sub>bus</sub> <sup>(1)</sup>	300	ns
	signals	f <sub>SCL</sub> = 100 kHz	20 + 0.1C <sub>bus</sub> <sup>(1)</sup>	1000	ns
t <sub>f</sub>	fall time of both SDA and SCL signals		20 + 0.1C <sub>bus</sub> <sup>(1)</sup>	300	ns
t <sub>SU;STO</sub>	set-up time for STOP condition		0.6	_	μs
C <sub>L(bus)</sub>	capacitive load for each bus line		_	400	pF
t <sub>SP</sub>	pulse width of spikes which must be suppressed by the input filter	f <sub>SCL</sub> = 400 kHz	0	50	ns

#### Note

1.  $C_{bus}$  = bus line capacitance in pF.

# **SAA2505H**



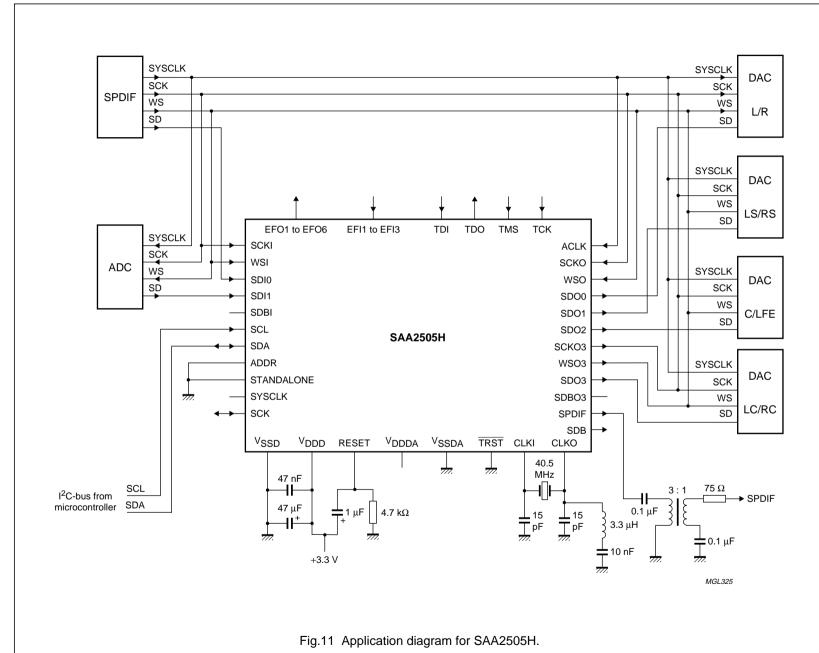
Philips Semiconductors

# **SAA2505H**

Philips Semiconductors

Preliminary specification

**APPLICATION INFORMATION** 

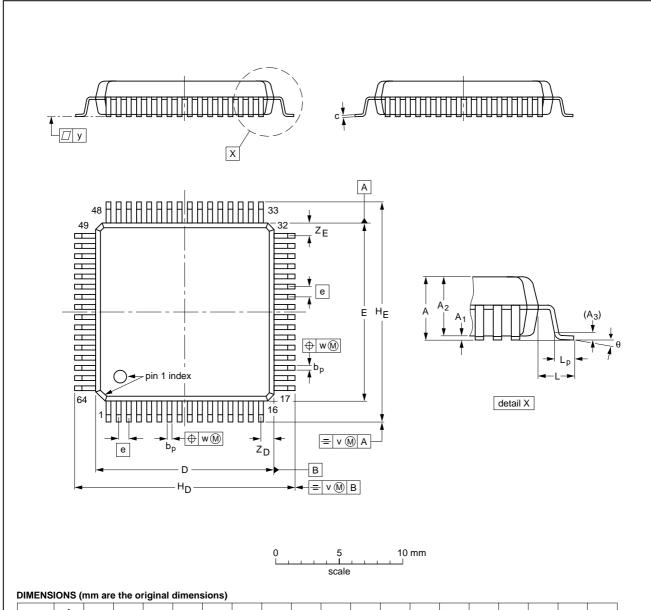


**SAA2505H** 

# **PACKAGE OUTLINE**

QFP64: plastic quad flat package; 64 leads (lead length 1.6 mm); body 14 x 14 x 2.7 mm

SOT393-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	H <sub>D</sub>	HE	L	Lp	v	w	у	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	3.00	0.25 0.10	2.75 2.55	0.25	0.45 0.30	0.23 0.13	14.1 13.9	14.1 13.9	0.8	17.45 16.95		1.60	1.03 0.73	0.16	0.16	0.10	1.2 0.8	1.2 0.8	7° 0°

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT393-1	134E07	MS-022				<del>99-12-27</del> 00-01-19

**SAA2505H** 

#### **SOLDERING**

#### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

# **Reflow soldering**

Reflow soldering techniques are suitable for all QFP packages.

The choice of heating method may be influenced by larger plastic QFP packages (44 leads, or more). If infrared or vapour phase heating is used and the large packages are not absolutely dry (less than 0.1% moisture content by weight), vaporization of the small amount of moisture in them can cause cracking of the plastic body. For more information, refer to the Drypack chapter in our "Quality Reference Handbook" (order code 9397 750 00192).

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 50 and 300 seconds depending on heating method. Typical reflow peak temperatures range from 215 to 250 °C.

# Wave soldering

Wave soldering is **not** recommended for QFP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

#### **CAUTION**

Wave soldering is NOT applicable for all QFP packages with a pitch (e) equal or less than 0.5 mm.

If wave soldering cannot be avoided, for QFP packages with a pitch (e) larger than 0.5 mm, the following conditions must be observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The footprint must be at an angle of 45° to the board direction and must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

# Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300  $^{\circ}$ C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320  $^{\circ}$ C.

# DUET digital multichannel audio IC

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#### **DATA SHEET STATUS**

DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

#### **Notes**

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

# **DEFINITIONS**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

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# DUET digital multichannel audio IC

**SAA2505H** 

# PURCHASE OF PHILIPS I2C COMPONENTS



Purchase of Philips  $I^2C$  components conveys a license under the Philips'  $I^2C$  patent to use the components in the  $I^2C$  system provided the system conforms to the  $I^2C$  specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

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NOTES

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NOTES

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